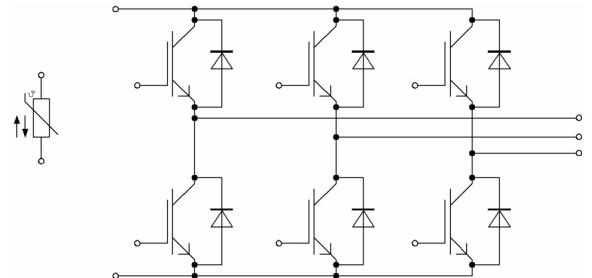
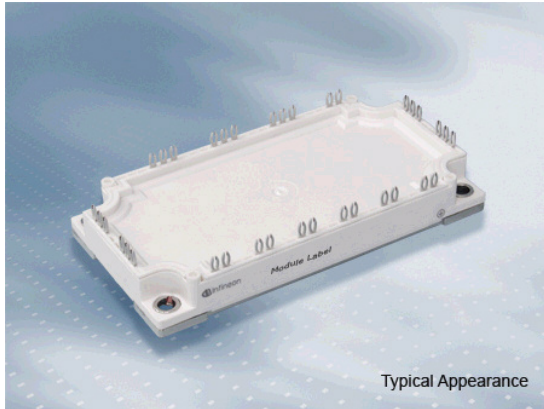


EconoPACK™3 Modul mit Trench/Feldstopp IGBT4 und Emitter Controlled Diode und PressFIT / NTC
EconoPACK™3 module with trench/fieldstop IGBT4 and Emitter Controlled Diode and PressFIT / NTC

Vorläufige Daten / Preliminary data



$V_{CES} = 1700V$
 $I_{C\ nom} = 100A / I_{CRM} = 200A$

Typische Anwendungen

- Motorantriebe
- USV-Systeme

Typical Applications

- Motor Drives
- UPS Systems

Elektrische Eigenschaften

- Erweiterte Sperrschichttemperatur $T_{vj\ op}$
- Niedriges V_{CEsat}
- V_{CEsat} mit positivem Temperaturkoeffizienten

Electrical Features

- Extended Operation Temperature $T_{vj\ op}$
- Low V_{CEsat}
- V_{CEsat} with positive Temperature Coefficient

Mechanische Eigenschaften

- Integrierter NTC Temperatur Sensor
- Isolierte Bodenplatte
- PressFIT Verbindungstechnik
- Standardgehäuse

Mechanical Features

- Integrated NTC temperature sensor
- Isolated Base Plate
- PressFIT Contact Technology
- Standard Housing

Module Label Code

Barcode Code 128



DMX - Code



Content of the Code

Digit

Module Serial Number	1 - 5
Module Material Number	6 - 11
Production Order Number	12 - 19
Datecode (Production Year)	20 - 21
Datecode (Production Week)	22 - 23

prepared by: AS	date of publication: 2012-01-13	material no: 35734
approved by: RS	revision: 2.0	UL approved (E83335)

IGBT-Wechselrichter / IGBT-inverter

Höchstzulässige Werte / Maximum Rated Values

Kollektor-Emitter-Sperrspannung Collector-emitter voltage	$T_{vj} = 25^{\circ}\text{C}$	V_{CES}	1700	V
Kollektor-Dauergleichstrom Continuous DC collector current	$T_C = 100^{\circ}\text{C}, T_{vj} = 175^{\circ}\text{C}$	$I_{C\text{ nom}}$	100	A
Periodischer Kollektor-Spitzenstrom Repetitive peak collector current	$t_p = 1\text{ ms}$	I_{CRM}	200	A
Gesamt-Verlustleistung Total power dissipation	$T_C = 25^{\circ}\text{C}, T_{vj} = 175^{\circ}\text{C}$	P_{tot}	600	W
Gate-Emitter-Spitzenspannung Gate-emitter peak voltage		V_{GES}	+/-20	V

Charakteristische Werte / Characteristic Values

			min.	typ.	max.	
Kollektor-Emitter-Sättigungsspannung Collector-emitter saturation voltage	$I_C = 100\text{ A}, V_{GE} = 15\text{ V}$ $I_C = 100\text{ A}, V_{GE} = 15\text{ V}$ $I_C = 100\text{ A}, V_{GE} = 15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$V_{CE\text{ sat}}$	1,95 2,35 2,45	2,30	V V V
Gate-Schwellenspannung Gate threshold voltage	$I_C = 4,00\text{ mA}, V_{CE} = V_{GE}, T_{vj} = 25^{\circ}\text{C}$		V_{GEth}	5,2 5,8	6,4	V
Gateladung Gate charge	$V_{GE} = -15\text{ V} \dots +15\text{ V}$		Q_G	1,20		μC
Interner Gatewiderstand Internal gate resistor	$T_{vj} = 25^{\circ}\text{C}$		R_{Gint}	7,5		Ω
Eingangskapazität Input capacitance	$f = 1\text{ MHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$		C_{ies}	9,00		nF
Rückwirkungskapazität Reverse transfer capacitance	$f = 1\text{ MHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$		C_{res}	0,29		nF
Kollektor-Emitter-Reststrom Collector-emitter cut-off current	$V_{CE} = 1700\text{ V}, V_{GE} = 0\text{ V}, T_{vj} = 25^{\circ}\text{C}$		I_{CES}		1,0	mA
Gate-Emitter-Reststrom Gate-emitter leakage current	$V_{CE} = 0\text{ V}, V_{GE} = 20\text{ V}, T_{vj} = 25^{\circ}\text{C}$		I_{GES}		400	nA
Einschaltverzögerungszeit, induktive Last Turn-on delay time, inductive load	$I_C = 100\text{ A}, V_{CE} = 900\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Gon} = 0,91\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_{d\text{ on}}$	0,20 0,22 0,23		μs μs μs
Anstiegszeit, induktive Last Rise time, inductive load	$I_C = 100\text{ A}, V_{CE} = 900\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Gon} = 0,91\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	t_r	0,03 0,04 0,05		μs μs μs
Abschaltverzögerungszeit, induktive Last Turn-off delay time, inductive load	$I_C = 100\text{ A}, V_{CE} = 900\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Goff} = 0,91\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_{d\text{ off}}$	0,51 0,61 0,64		μs μs μs
Fallzeit, induktive Last Fall time, inductive load	$I_C = 100\text{ A}, V_{CE} = 900\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Goff} = 0,91\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	t_f	0,29 0,52 0,60		μs μs μs
Einschaltverlustenergie pro Puls Turn-on energy loss per pulse	$I_C = 100\text{ A}, V_{CE} = 900\text{ V}, L_S = 50\text{ nH}$ $V_{GE} = \pm 15\text{ V}, di/dt = 3800\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $R_{Gon} = 0,91\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	E_{on}	12,0 19,0 21,0		mJ mJ mJ
Abschaltverlustenergie pro Puls Turn-off energy loss per pulse	$I_C = 100\text{ A}, V_{CE} = 900\text{ V}, L_S = 50\text{ nH}$ $V_{GE} = \pm 15\text{ V}, du/dt = 3600\text{ V}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $R_{Goff} = 0,91\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	E_{off}	18,0 29,0 33,0		mJ mJ mJ
Kurzschlußverhalten SC data	$V_{GE} \leq 15\text{ V}, V_{CC} = 1000\text{ V}$ $V_{CEmax} = V_{CES} - L_{sCE} \cdot di/dt$ $t_p \leq 10\ \mu\text{s}, T_{vj} = 150^{\circ}\text{C}$		I_{SC}	450		A
Wärmewiderstand, Chip bis Gehäuse Thermal resistance, junction to case	pro IGBT / per IGBT		R_{thJC}		0,25	K/W
Wärmewiderstand, Gehäuse bis Kühlkörper Thermal resistance, case to heatsink	pro IGBT / per IGBT $\lambda_{Paste} = 1\text{ W}/(\text{m}\cdot\text{K})$ / $\lambda_{grease} = 1\text{ W}/(\text{m}\cdot\text{K})$		R_{thCH}	0,068		K/W

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Vorläufige Daten
Preliminary data

Diode-Wechselrichter / Diode-inverter
Höchstzulässige Werte / Maximum Rated Values

Periodische Spitzensperrspannung Repetitive peak reverse voltage	$T_{vj} = 25^{\circ}\text{C}$	V_{RRM}	1700	V
Dauergleichstrom Continuous DC forward current		I_F	100	A
Periodischer Spitzenstrom Repetitive peak forward current	$t_p = 1 \text{ ms}$	I_{FRM}	200	A
Grenzlastintegral I^2t - value	$V_R = 0 \text{ V}, t_p = 10 \text{ ms}, T_{vj} = 125^{\circ}\text{C}$ $V_R = 0 \text{ V}, t_p = 10 \text{ ms}, T_{vj} = 150^{\circ}\text{C}$	I^2t	1800 1750	A^2s A^2s

Charakteristische Werte / Characteristic Values

			min.	typ.	max.	
Durchlassspannung Forward voltage	$I_F = 100 \text{ A}, V_{GE} = 0 \text{ V}$ $I_F = 100 \text{ A}, V_{GE} = 0 \text{ V}$ $I_F = 100 \text{ A}, V_{GE} = 0 \text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	V_F	1,80 1,90 1,95	2,20	V V V
Rückstromspitze Peak reverse recovery current	$I_F = 100 \text{ A}, -di_F/dt = 3800 \text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 900 \text{ V}$ $V_{GE} = -15 \text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	I_{RM}	110 120 125		A A A
Sperrverzögerungsladung Recovered charge	$I_F = 100 \text{ A}, -di_F/dt = 3800 \text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 900 \text{ V}$ $V_{GE} = -15 \text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	Q_r	19,0 36,0 40,0		μC μC μC
Abschaltenergie pro Puls Reverse recovery energy	$I_F = 100 \text{ A}, -di_F/dt = 3800 \text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 900 \text{ V}$ $V_{GE} = -15 \text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	E_{rec}	10,0 20,0 23,0		mJ mJ mJ
Wärmewiderstand, Chip bis Gehäuse Thermal resistance, junction to case	pro Diode / per diode		R_{thJC}		0,40	K/W
Wärmewiderstand, Gehäuse bis Kühlkörper Thermal resistance, case to heatsink	pro Diode / per diode $\lambda_{paste} = 1 \text{ W}/(\text{m}\cdot\text{K}) / \lambda_{grease} = 1 \text{ W}/(\text{m}\cdot\text{K})$		R_{thCH}		0,27	K/W

NTC-Widerstand / NTC-thermistor

Charakteristische Werte / Characteristic Values

			min.	typ.	max.	
Nennwiderstand Rated resistance	$T_C = 25^{\circ}\text{C}$		R_{25}	5,00		k Ω
Abweichung von R100 Deviation of R100	$T_C = 100^{\circ}\text{C}, R_{100} = 493 \Omega$		$\Delta R/R$	-5	5	%
Verlustleistung Power dissipation	$T_C = 25^{\circ}\text{C}$		P_{25}		20,0	mW
B-Wert B-value	$R_2 = R_{25} \exp [B_{25/50}(1/T_2 - 1/(298,15 \text{ K}))]$		$B_{25/50}$	3375		K
B-Wert B-value	$R_2 = R_{25} \exp [B_{25/80}(1/T_2 - 1/(298,15 \text{ K}))]$		$B_{25/80}$	3411		K
B-Wert B-value	$R_2 = R_{25} \exp [B_{25/100}(1/T_2 - 1/(298,15 \text{ K}))]$		$B_{25/100}$	3433		K

Angaben gemäß gültiger Application Note.
Specification according to the valid application note.

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Technische Information / technical information

IGBT-Module
IGBT-modules

FS100R17N3E4_B11



Vorläufige Daten Preliminary data

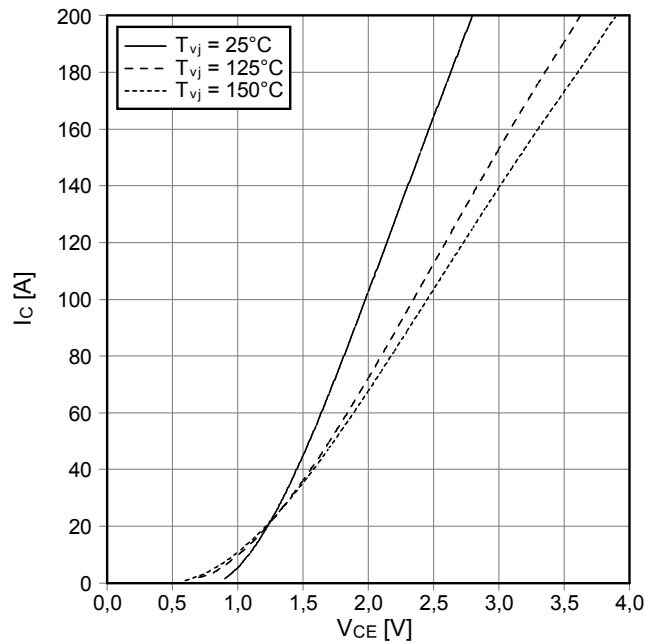
Modul / Module

Isolations-Prüfspannung Isolation test voltage	RMS, f = 50 Hz, t = 1 min.	V _{ISOL}	3,4		kV
Material Modulgrundplatte Material of module baseplate			Cu		
Innere Isolation Internal isolation			Al ₂ O ₃		
Kriechstrecke Creepage distance	Kontakt - Kühlkörper / terminal to heatsink Kontakt - Kontakt / terminal to terminal		10,0		mm
Luftstrecke Clearance	Kontakt - Kühlkörper / terminal to heatsink Kontakt - Kontakt / terminal to terminal		7,5		mm
Vergleichszahl der Kriechwegbildung Comperative tracking index		CTI	> 200		
			min.	typ.	max.
Wärmewiderstand, Gehäuse bis Kühlkörper Thermal resistance, case to heatsink	pro Modul / per module $\lambda_{\text{Paste}} = 1 \text{ W}/(\text{m}\cdot\text{K}) / \lambda_{\text{grease}} = 1 \text{ W}/(\text{m}\cdot\text{K})$	R _{thCH}	0,009		K/W
Modulstreuintduktivität Stray inductance module		L _{sCE}	28		nH
Modulleitungswiderstand, Anschlüsse - Chip Module lead resistance, terminals - chip	T _C = 25°C, pro Schalter / per switch	R _{CC'+EE'}	1,80		mΩ
Höchstzulässige Sperrschichttemperatur Maximum junction temperature	Wechselrichter, Brems-Chopper / Inverter, Brake-Chopper	T _{vj max}			175 °C
Temperatur im Schaltbetrieb Temperature under switching conditions	Wechselrichter, Brems-Chopper / Inverter, Brake-Chopper	T _{vj op}	-40		150 °C
Lagertemperatur Storage temperature		T _{stg}	-40		125 °C
Anzugsdrehmoment f. Modulmontage Mounting torque for modul mounting	Schraube M5 - Montage gem. gültiger Applikation Note screw M5 - mounting according to valid application note	M	3,00	-	6,00 Nm
Gewicht Weight		G	300		g

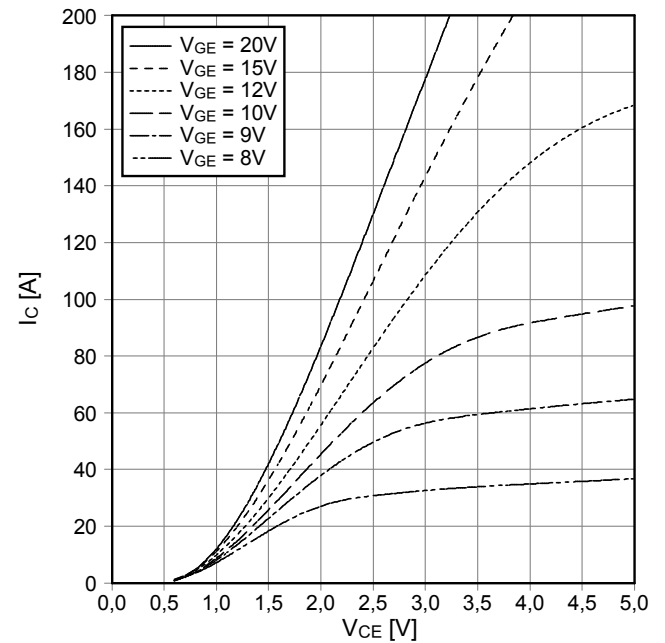
prepared by: AS	date of publication: 2012-01-13
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Vorläufige Daten
Preliminary data

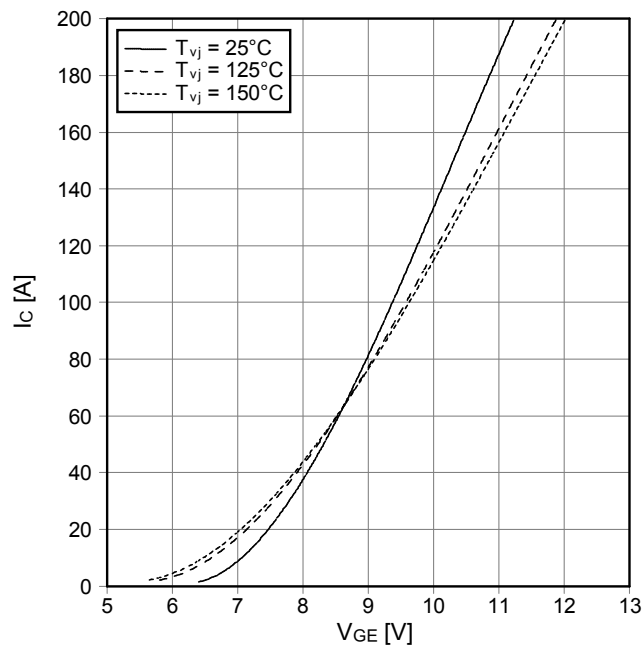
Ausgangskennlinie IGBT-Wechselr. (typisch)
output characteristic IGBT-inverter (typical)
 $I_c = f(V_{CE})$
 $V_{GE} = 15\text{ V}$



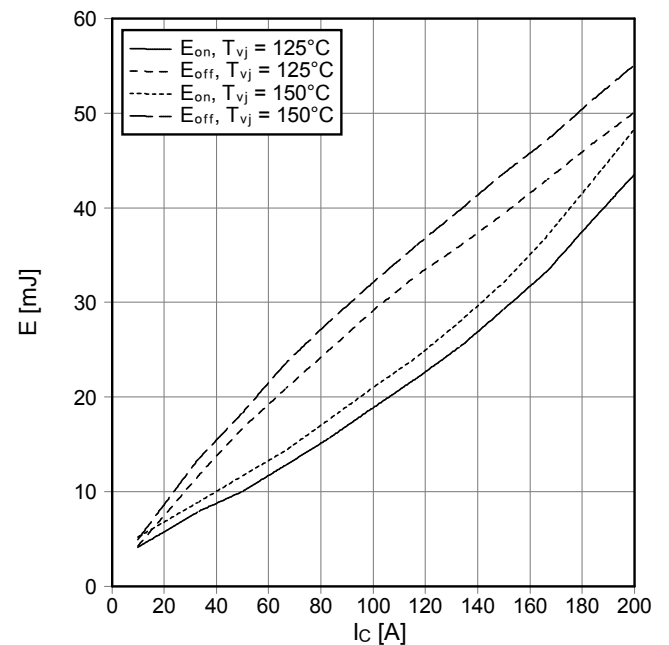
Ausgangskennlinienfeld IGBT-Wechselr. (typisch)
output characteristic IGBT-inverter (typical)
 $I_c = f(V_{CE})$
 $T_{vj} = 150^\circ\text{C}$



Übertragungscharakteristik IGBT-Wechselr. (typisch)
transfer characteristic IGBT-inverter (typical)
 $I_c = f(V_{GE})$
 $V_{CE} = 20\text{ V}$



Schaltverluste IGBT-Wechselr. (typisch)
switching losses IGBT-inverter (typical)
 $E_{on} = f(I_c)$, $E_{off} = f(I_c)$
 $V_{GE} = \pm 15\text{ V}$, $R_{Gon} = 0.91\ \Omega$, $R_{Goff} = 0.91\ \Omega$, $V_{CE} = 900\text{ V}$

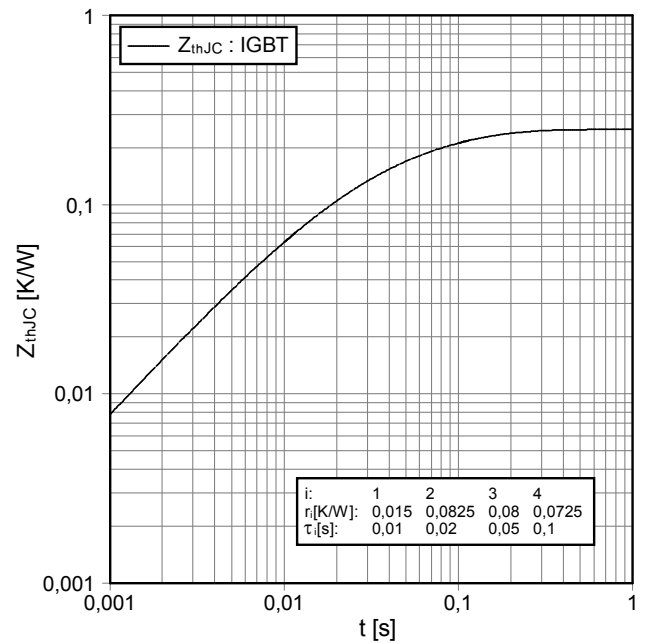
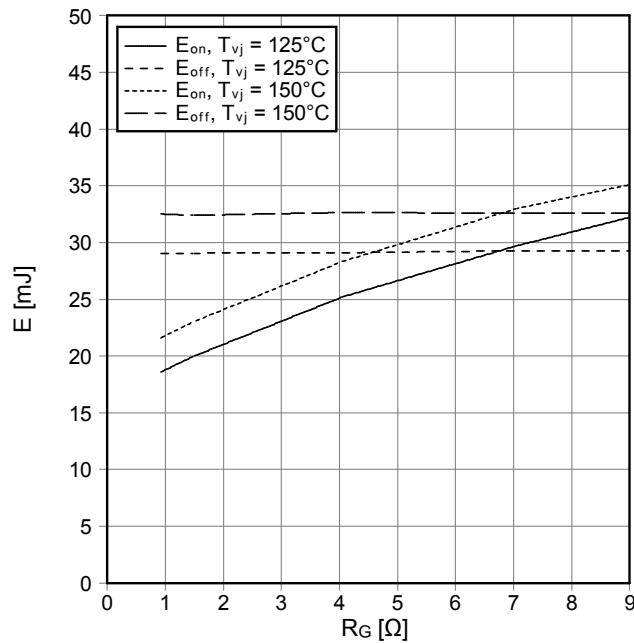


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Vorläufige Daten
Preliminary data

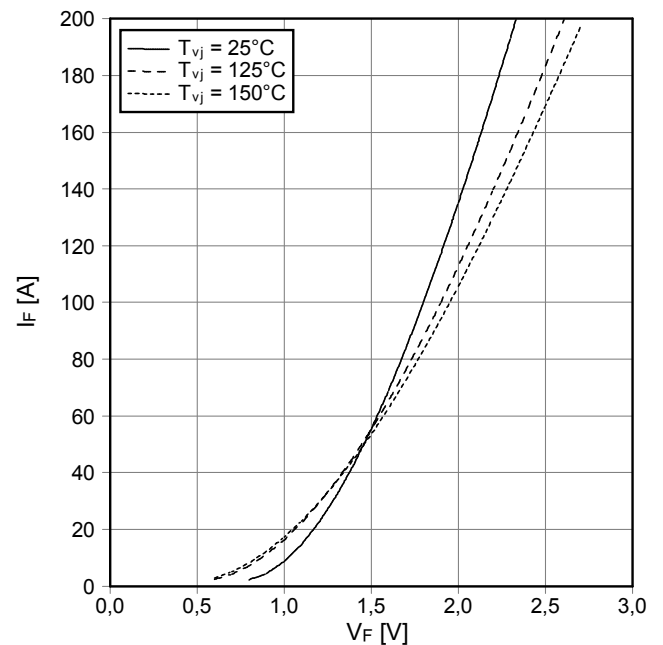
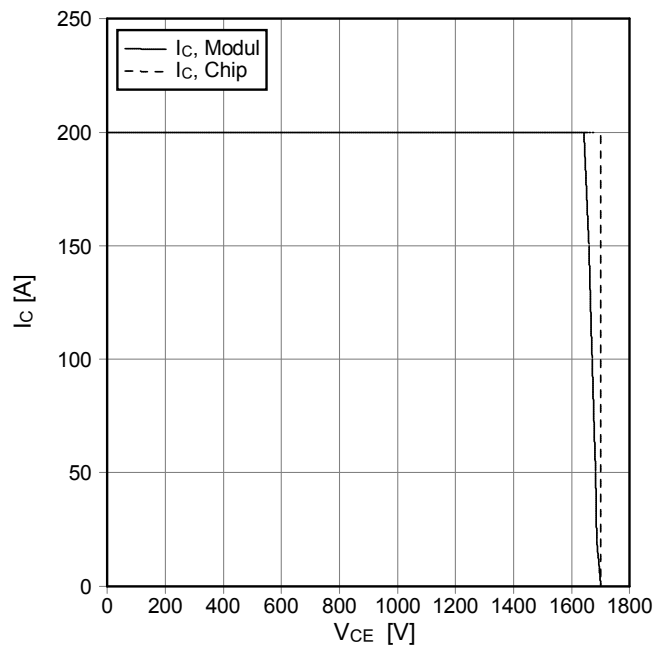
Schaltverluste IGBT-Wechslr. (typisch)
switching losses IGBT-inverter (typical)
 $E_{on} = f(R_G), E_{off} = f(R_G)$
 $V_{GE} = \pm 15\text{ V}, I_C = 100\text{ A}, V_{CE} = 900\text{ V}$

Transienter Wärmewiderstand IGBT-Wechslr.
transient thermal impedance IGBT-inverter
 $Z_{thJC} = f(t)$



Sicherer Rückwärts-Arbeitsbereich IGBT-Wr. (RBSOA)
reverse bias safe operating area IGBT-inv. (RBSOA)
 $I_C = f(V_{CE})$
 $V_{GE} = \pm 15\text{ V}, R_{Goff} = 0.91\ \Omega, T_{vj} = 150^\circ\text{C}$

Durchlasskennlinie der Diode-Wechslr. (typisch)
forward characteristic of diode-inverter (typical)
 $I_F = f(V_F)$

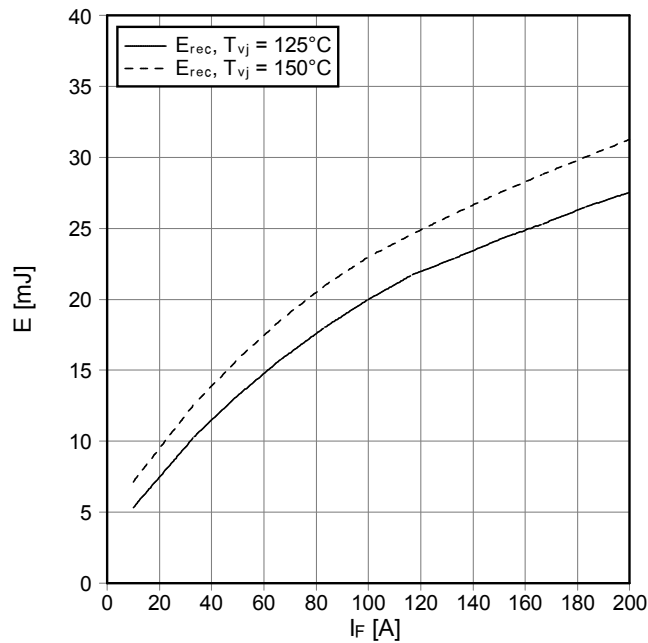


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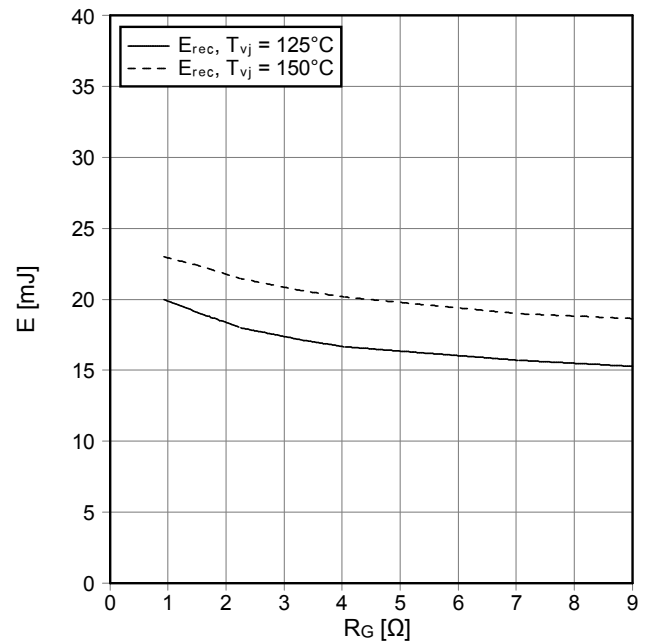


Vorläufige Daten
Preliminary data

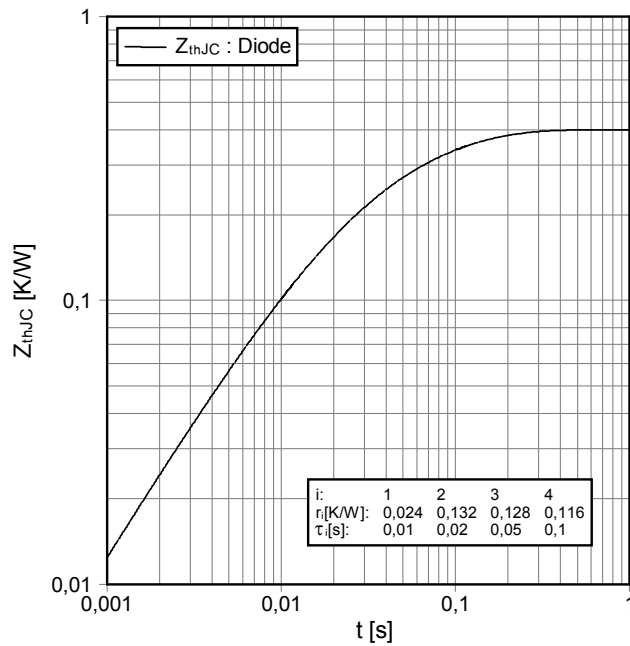
Schaltverluste Diode-Wechselr. (typisch)
switching losses diode-inverter (typical)
 $E_{rec} = f(I_F)$
 $R_{Gon} = 0.91 \Omega, V_{CE} = 900 V$



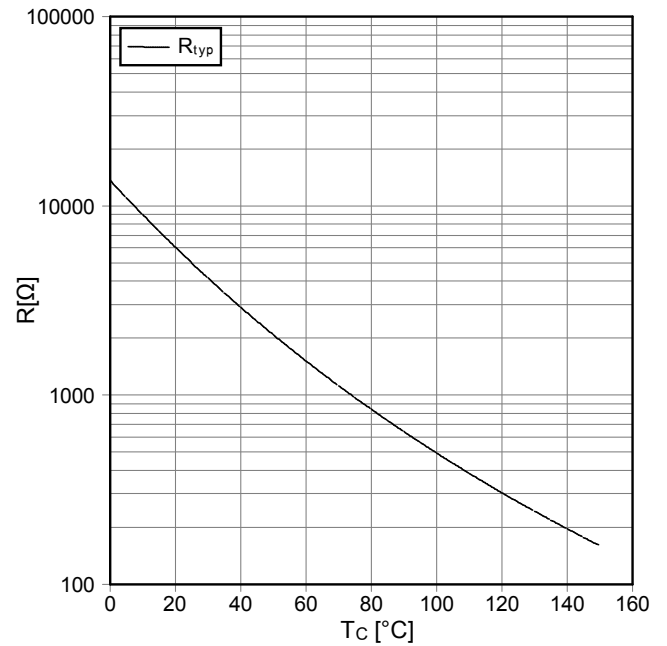
Schaltverluste Diode-Wechselr. (typisch)
switching losses diode-inverter (typical)
 $E_{rec} = f(R_G)$
 $I_F = 100 A, V_{CE} = 900 V$



Transienter Wärmewiderstand Diode-Wechselr.
transient thermal impedance diode-inverter
 $Z_{thJC} = f(t)$

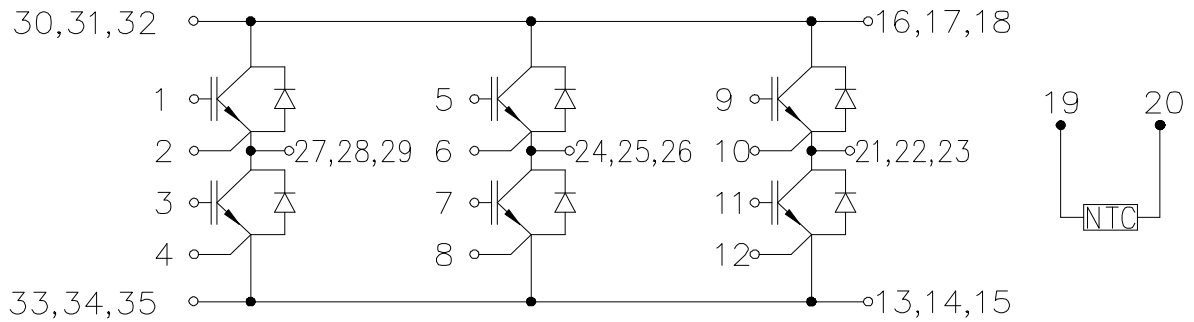


NTC-Temperaturkennlinie (typisch)
NTC-temperature characteristic (typical)
 $R = f(T)$

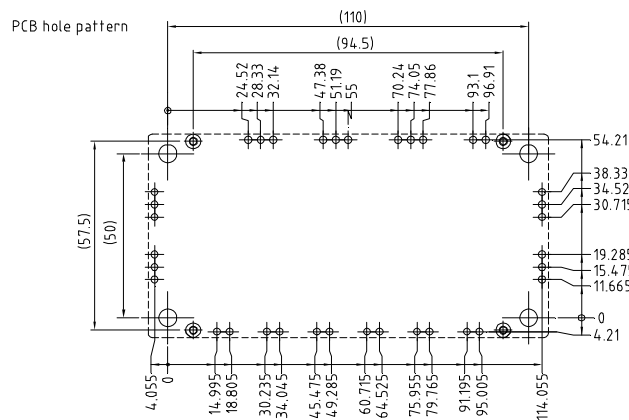
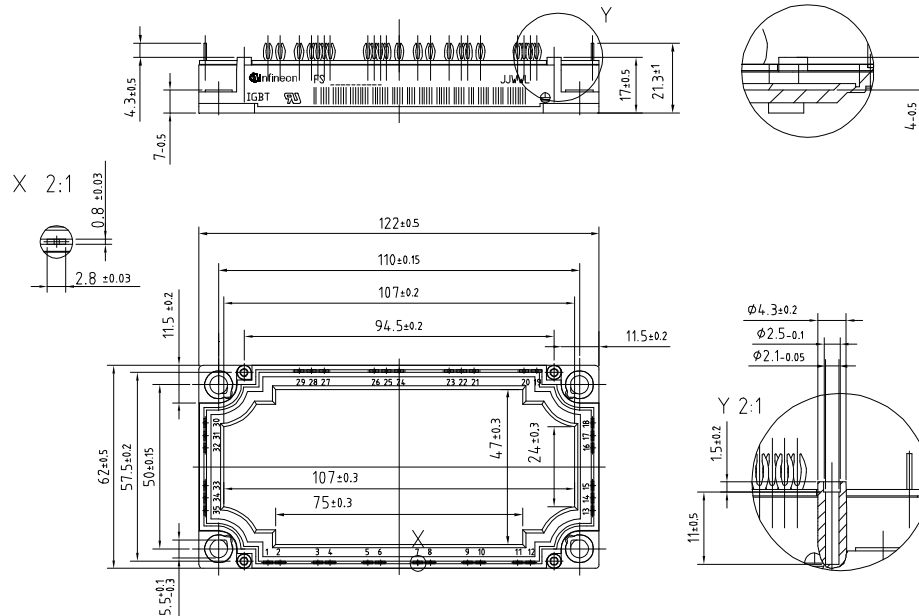


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Schaltplan / circuit diagram



Gehäuseabmessungen / package outlines



- Tolerance of PCB hole pattern ± 0.1
- hole specifications see AN 2007-09
- Diameters of plated holes $\varnothing 2.14\text{mm} - 2.29\text{mm}$
- Diameter of drill $\varnothing 2.35\text{mm}$

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